connection strands arranged on said substrate in a single plane and extending in a planar direction over the entire substrate surface and having a longitudinal expansion flush with the substrate surface.

2. (AMENDED) A chip carrier according to claim 1, wherein the carrier film is provided with at least one additional conductive counter-strand on a side opposite the connection strands to generate a capacitance, wherein the insulating carrier film is arranged as an intermediate layer between the connection strands on the one hand and the counter-strand on the other.

3. (AMENDED) A chip carrier according to claim 1, wherein said connection strands are at least sectionally provided with a connecting material coating for contacting with the contact metallizations of a chip.

4. (AMENDED) A chip carrier according to claim 1, wherein said connection strands are at least sectionally provided with a contact metallization for contacting with the contact metallizations of a chip.

5. (AMENDED) A chip carrier according to claim 1, wherein said connection strands are connected with the terminals of a coil unit.

6. (AMENDED) A chip module, comprising:

a chip carrier comprising a substrate formed by a carrier film and connection leads arranged on the substrate, said connection leads comprising stripes and extend parallel over the substrate, said connection leads comprising electrically conductive connection strands arranged on said substrate in a single plane and extending in a planar direction over the entire substrate surface and having a longitudinal expansion flush with the substrate surface; and

connecting surfaces with elevated contact metallizations, said contact metallizations being in contact with a top side of said connection strands facing away from the carrier film.

7. (AMENDED) A chip module according to claim 6, wherein the connection strands are in contact with the contact metallizations of the chip and are connected with the terminals of a coil unit.

8. (AMENDED) A method of manufacturing a chip module with a chip carrier comprising a substrate formed by a carrier film and connection leads arranged on the substrate, said connection leads comprising stripes and extend parallel over the substrate, said connection leads comprising electrically conductive connection strands arranged on said substrate in a single plane and extending in a planar direction over the entire substrate surface and having a longitudinal expansion flush with the substrate surface and connecting surfaces with elevated contact metallizations, said contact metallizations being in contact with a top side of said connection strands facing away from the carrier film, the method comprising the steps of:

applying at least two electrically conductive connection strands to one side of the carrier film so that connection strands lie parallel to each other in a single plane, and extend in a planar direction over the carrier film; and

contacting contact metallizations of the chip with the connection strands, so that a contact metallization of the chip is contacted with a respective connection strand.

9. (AMENDED) A method of manufacturing a chip module according to claim 8, wherein the connection strands are contacted with a coil unit before contacting the connection strands with the chip.

10. (AMENDED) A method of manufacturing a chip module according to claim 8, wherein the connection strands are continuously applied to the carrier film in such a way that the connection strands and carrier film are provided as continuous strands, and moved against each other continuously in a contact area while forming an adhesion.

11. (AMENDED) A method according to claim 10, wherein the carrier film is provided with window openings at defined distances before forming the contact area with the connection strands, so that the window openings in the subsequently formed contact area are covered by the connection strands while forming pocket-like contact receptacles.

12. (AMENDED) A method according to claim 8, wherein the carrier film is coated